

YTX-3000 Series X-Ray

High Resolution X-Ray System

- **High Performance**
- **Maintenance Free**
- **Cost Effective**
- **Superior Software**



The YTX-3000 X-ray system offers EMS providers and semiconductor packagers a superior yield enhancement solution to reduce costs, improve quality and increase throughput.

The YESTech YTX-3000 provides users with a high-resolution x-ray capability in a flexible, compact maintenance free configuration. The YTX-3000 is available with a 4 or 5 axis sample manipulator and a 15" x 20" (380mm x 508mm) x-y travel for samples up to 5 pounds in weight. Full 360 degrees of rotation and 30 degrees of tilt are available. Stepper motor drives provide a wide range of motion from ultra-slow use at high magnifications, to high speed for travel over large distances. All systems come with a unique control module and programmable motion for automated inspection.

The YTX-3000 comes with YESTech's proprietary machine vision technology for fully automated inspection of BGA and flip chip devices. Other optional inspections include die attach, bond wire and correct assembly verification.

X-RAY INSPECTION FOR:

- **BGA / Flip Chip**
- **Solder joint quality**
 - **VOIDS**
- **Bond wires**
- **Electronic and sealed assemblies**
 - **Paste**

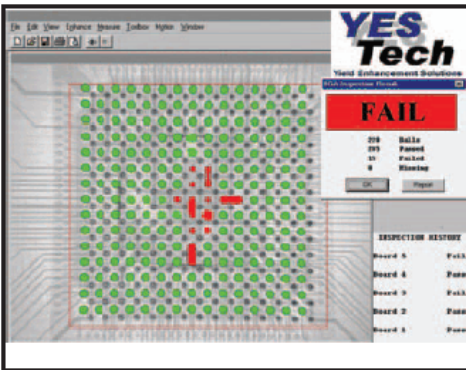
YESTech

"World Leader in Automated Optical Inspections and X-Ray Inspection Systems"

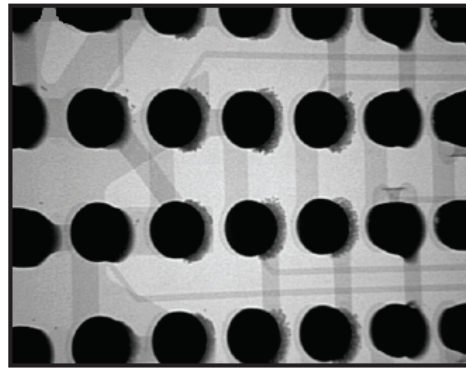
SPECIFICATIONS*

X-Ray Tube	Maintenance free Sealed reflection target 130 Kv, 5 micron spot size 39-watt max. output
Sample Manipulator	15"x 20"x 18" (380mm x 508mm x 457mm) x-y-z-theta programmable indexing table with control module. Optional tilt available. Variable zoom magnification to 120x.
Cabinet	49"x 48" x 80" (1245mm x 1220mm x 2032mm) cabinet with 18" x 18" (457mm x 457mm) door and viewing window
Software	BGA, Void, Wire Sweep, Off-set, 3-D
Safety	YESTech x-ray systems are manufactured to comply with the federal standard for cabinet x-ray equipment as established in Title 21, Subchapter J of the code of federal regulation sections 1020.40. Lead is used to line the cabinet and door, with lead doped glass for the viewing window. Interlock switches ensure that x-ray radiation can not be generated with any part of the cabinet open or removed.
Facilities	Power: 110 VAC (220 optional) 50 / 60 Hz 15amps Weight: 2,000 lbs. (907Kg) Machine installation: < 1 hour

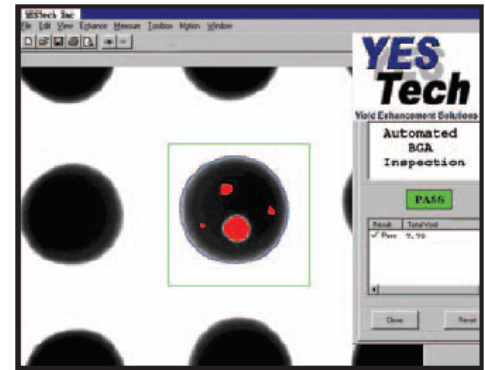
* Specifications subject to change



Automated BGA inspection and SPC software.



Rotated view of micro-BGA showing unreflowed solder joints.



Automated void calculation.



Vietnam's leading supplier of semiconductor interconnect assembly equipment.

www.acrosemi.com

Email: sales@acrosemi.com

U.S.A Office

4930 W. Flight Ave.,
Santa Ana, California 92704, U.S.A.
Tel: 714-468-9034
Fax: 866-212-8857
Email: sales@acrosemi.com

Ho Chi Minh Office

404 Plot G, Tan Binh IZ, Tan Phu Dist.,
Ho Chi Minh City, Vietnam
Tel: (+84 8) 6 674-2919
Fax: (+84 8) 268-0957
Email: hcmc@acrosemi.com

Hanoi Office

1, Dai Co Viet Road,
Hanoi City, Vietnam
Tel: (+84) 91-225-7173
Fax: (+001) 866-212-8857
Email: hanoi@acrosemi.com